EMDXM SERIES

MINIATURE SINGLE-PHASE BRIDGE RECTIFIER

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EMD1M THRU EMD4M

MINIATURE GLASS PASSIVATED SUPER FAST SINGLE-PHASE BRIDGE RECTIFIER



REVERSE VOLTAGE: FORWARD CURRENT:

50 to 200 VOLTS 0.5 AMPERE

FEATURES

· Glass passivated chip junction

· Super fast recovery, low switching loss

· High surge overload rating of 25 Amperes peak

· Ideal for printed circuit board

 \cdot High temperature soldering guaranteed:

260°C for 10 seconds

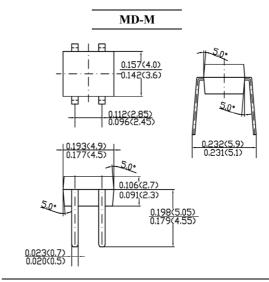
MECHANICAL DATA

Case: Molded plastic, MD-M

Epoxy: UL 94V-O rate flame retardant

Terminals: Leads solderable per MIL-STD-202,

method 208 guaranteed Mounting position: Any Weight: 0.008ounce, 0.22gram



Dimensions in inches and (millimeters)

Maximum Ratings and Electrical Characteristics

Ratings at 25 ambient temperature unless otherwise specified.

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitive load, derate current by 20%.

	Symbols	EMD1M	EMD2M	EMD3M	EMD4M	Units
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	50	100	150	200	Volts
Maximum RMS Voltage	V_{RMS}	35	70	105	140	Volts
Maximum DC Blocking Voltage	V_{DC}	50	100	150	200	Volts
Maximum Average Forward Rectified Current			•		•	
(see Fig. 1) on glass-epoxy P.C.B (Note 2)	$I_{(AV)}$	0.5				Amp
on aluminum substrate (Note 3)		0.8				
Peak Forward Surge Current,						
8.3ms single half-sine-wave	I_{FSM} 25					Amp
superimposed on rated load (JEDEC method)						
Maximum Forward Voltage	V_{F}	1.05				Volts
at 0.4A DC and 25	V F					
Maximum Reverse Current at T _A =25	I_R	5.0				uAmp
at Rated DC Blocking Voltage T _A =125	1R	500				
Typical Junction Capacitance (Note 1)	C_{J}	13				pF
Maximum Reverse Recovery Time (Note 4)	T_{RR}	50				nS
Typical Thermal Resistance (Note 3)	$R_{\theta JA}$	70				/W
Typical Thermal Resistance (Note 2)	$R_{\theta JL}$	20				/W
Operating and Storage Temperature Range	T _J , Tstg	-55 to +150				

NOTES:

- 1- Measured at 1 $\ensuremath{\text{MH}_{\text{Z}}}$ and applied reverse voltage of 4.0 VDC.
- 2- On glass epoxy P.C.B. mounted on 0.05 x 0.05" (1.3 x 1.3mm) pads
- 3- On aluminum substrate P.C.B. with an area of 0.8" x 0.8" (20 x 20mm) mounted on 0.05 x 0.05" (1.3 x 1.3mm) solder pad
- 4- Reverse Recovery Test Conditions: $\rm I_F = .5A$, $\rm I_R = 1A$, $\rm I_{RR} = .25A$.



RATINGS AND CHARACTERISTIC CURVES

